PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CUBIC WAFER, INC.	03/21/2008

RECEIVING PARTY DATA

Name:	CUFER ASSET LTD. L.L.C.
Street Address:	1209 Orange Street
City:	Wilmington
State/Country:	DELAWARE
Postal Code:	19801

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11329540

OP $40.00 11329540

CORRESPONDENCE DATA

Fax Number: (608)258-4258
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Email: MadisonIPDocketing@foley.com, wmorris@foley.com
Correspondent Name: Paul S Hunter, Foley & Lardner LLP
Address Line 1: Verex Plaza
Address Line 2: 150 East Gilman Street
Address Line 4: Madison, WISCONSIN 53703-1481

ATTORNEY DOCKET NUMBER:	088245-4704
NAME OF SUBMITTER:	Paul S. Hunter

Total Attachments: 19
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Exhibit B

ASSIGNMENT OF PATENT RIGHTS

For good and valuable consideration, the receipt of which is hereby acknowledged, Cubic Wafer, Inc., a Delaware corporation, with an office at 205 Wildbasin Road, Building 3, Suite 200, Austin, TX 78746 (***"Assignor"***), does hereby sell, assign, transfer, and convey unto Cufer Asset Ltd. L.L.C., a Delaware limited liability company, with an address at 1209 Orange Street. Wilmington, DE 19801 (***"Assignee"***), or its designees, all right, title, and interest that exist today and may exist in the future in and to any and all of the following (collectively, the ***"Patent Rights"***):

(a) the provisional patent applications, patent applications and patents listed in the table below (the "***Patents***");

(b) all patents and patent applications (i) to which any of the Patents directly or indirectly claims priority, (ii) for which any of the Patents directly or indirectly forms a basis for priority, and/or (iii) that were co-owned applications that incorporate by reference, or are incorporated by reference into, the Patents;

(c) all reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, requests for continuing examinations, divisions, registrations of any item in any of the foregoing categories (a) and (b);

(d) all foreign patents, patent applications, and counterparts relating to any item in any of the foregoing categories (a) through (c), including, without limitation, certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants or issuances;

(e) all items in any of the foregoing in categories (b) through (d), whether or not expressly listed as Patents below and whether or not claims in any of the foregoing have been rejected, withdrawn, cancelled, or the like;

(f) inventions, invention disclosures, and discoveries described in any of the Patents and/or any item in the foregoing categories (b) through (e) that (i) are included in any claim in the Patents and/or any item in the foregoing categories (b) through (e), (ii) are subject matter capable of being reduced to a patent claim in a reissue or reexamination proceedings brought on any of the Patents and/or any item in the foregoing categories (b) through (e), and/or (iii) could have been included as a claim in any of the Patents and/or any item in the foregoing categories (b) through (e);

(g) all rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections, or other governmental grants or issuances of any type related to any item in any of the foregoing categories (a) through (f), including, without limitation, under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement, or understanding;

(h) all causes of action (whether known or unknown or whether currently pending, filed, or otherwise) and other enforcement rights under, or on account of, any of the Patents and/or any item in any of the foregoing categories (b) through (g), including, without limitation, all causes of action and other enforcement rights for

(1) damages,
(2) injunctive relief, and
(3) any other remedies of any kind

for past, current, and future infringement; and

(i) all rights to collect royalties and other payments under or on account of any of the Patents and/or any item in any of the foregoing categories (b) through (h).

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
5,923,951 (08/688,131)	US	7/13/1999 (7/29/1996)	METHOD OF MAKING A FLIP-CHIP BONDED GAS-BASED OPTO-ELECTRONIC DEVICE Goossen, Keith Wayne; Kuo, Jenn-Ming; Wang, Yu-Chi
6,005,240 (09/032,545)	US	12/21/1999 (2/26/1998)	Triggered receivers for optoelectronic-VLSI circuits Krishnamoorthy, Ashok V
6,005,262 (09/014,196)	US	12/21/1999 (1/27/1998)	Flip-chip bonded VCSEL CMOS circuit with silicon monitor detector Cunningham, John; Goossen, Keith; Krishnamoorthy, Ashok
6,067,307 (09/096,802)	US	5/23/2000 (6/12/1998)	Vertical cavity surface emitting laser driving circuit Krishnamoorthy, Ashok V
6,388,322 (09/764,192)	US	5/14/2002 (1/17/2001)	Article comprising a mechanically compliant bump Goossen, Keith W; Jan, William Y
6,458,411 (09/971,764)	US	10/1/2002 (10/5/2001)	Method of making a mechanically compliant bump Goossen, Keith W; Jan, William Y
6,420,778 (09/872,569)	US	7/16/2002 (6/1/2001)	Differential electrical transmission line structures employing crosstalk compensation and related methods Sinyansky, Victor

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
6,424,450 (09/726,179)	US	7/23/2002 (11/29/2000)	Optical modulator having low insertion loss and wide bandwidth Goossen, Keith W
6,501,589 (09/791,247)	US	12/31/2002 (2/22/2001)	Article comprising a metallic anti-mirror Goossen, Keith W
6,604,866 (10/090,880)	US	8/12/2003 (3/4/2002)	Optical fiber ferrule Kang, Keith; Trezza, John
CA2477801	CA	3/3/2003	OPTICAL FIBER FERRULE Trezza, John; Kang, Keith
CN03805137.0	CN	3/3/2003	Optical fiber ferrule Kang, Keith; Trezza, John
EP03716257.5	EP	3/3/2003	OPTICAL FIBER FERRULE Kang, Keith; Trezza, John
KR10-2004-7013843	KR	3/3/2003	OPTICAL FIBER FERRULE Kang, Keith; Trezza, John
SG105996 (SG200404751-8)	SG	(3/3/2003)	OPTICAL FIBER FERRULE Kang, Keith; Trezza, John
6,913,397 (10/463,294)	US	7/5/2005 (6/17/2003)	Method and system for insertion of fibers of a fiber cable into a ferrule Kang, Keith; Kang, Misu; Otto, Robert
CA2494726	CA	7/3/2003	METHOD AND SYSTEM FOR INSERTION OF FIBERS OF A FIBER CABLE INTO A FERRULE Otto, Robert; Kang, Misu; Kang, Keith
CN03823231.6	CN	7/3/2003	Method and system for insertion of fibers of a fiber cable into a ferrule Kang, Keith; Kang, Misu; Otto, Robert
EP03748945.7	EP	7/3/2003	METHOD AND SYSTEM FOR INSERTION OF FIBERS OF A FIBER CABLE INTO A FERRULE Kang, Keith; Kang, Misu; Otto, Robert

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
6,880,980 (10/623,435)	US	4/19/2005 (7/18/2003)	Optical fiber ferrule Kang, Keith; Trezza, John
KR10-2005-7001778	KR	1/31/2005	METHOD AND SYSTEM FOR INSERTION OF FIBERS OF A FIBER CABLE INTO A FERRULE Kang, Keith; Kang, Misu; Otto, Robert
6,620,642 (09/896,189)	US	9/16/2003 (6/29/2001)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
6,773,166 (09/896,664)	US	8/10/2004 (6/29/2001)	MULTI-PIECE FIBER OPTIC COMPONENT AND MANUFACTURING TECHNIQUE Trezza, John; Dudoff, Greg; Kang, Keith; Olson, Ronald
09/896,797	US	6/29/2001	Redundant optical device array Trezza, John
6,790,691 (09/896,983)	US	9/14/2004 (6/29/2001)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
6,753,197 (09/897,158)	US	6/22/2004 (6/29/2001)	OPTO-ELECTRONIC DEVICE INTEGRATION Greg Dudoff , Amherst, NH
6,724,794 (09/897,160)	US	4/20/2004 (6/29/2001)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
CA2447373	CA	6/21/2002	REDUNDANT OPTICAL DEVICE ARRAY Trezza, John
CN02813098.7	CN	6/21/2002	Redundant optical device array Trezza, John
KR10-2003-7016817	KR	6/21/2002	REDUNDANT OPTICAL DEVICE ARRAY Trezza, John
SG101696 (SG200307580-1)	SG	(6/21/2002)	REDUNDANT OPTICAL DEVICE ARRAY Trezza, John
6,989,945 (10/180,241)	US	1/24/2006 (6/26/2002)	LONG-THROW, TIGHT FOCUSING OPTICAL COUPLER Kang, Keith; Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
6,731,665 (10/180,367)	US	5/4/2004 (6/26/2002)	LASER ARRAYS FOR HIGH POWER FIBER AMPLIFIER PUMPS Trezza, John
6,774,715 (10/180,369)	US	8/10/2004 (6/26/2002)	BICMOS AC FILTER CIRCUIT Wyman, Ted; Kiamilev, Fouad
6,753,199 (10/180,383)	US	6/22/2004 (6/26/2002)	TOPSIDE ACTIVE OPTICAL DEVICE APPARATUS AND METHOD Faska, Tom; Dudoff, Greg
6,775,308 (10/180,603)	US	8/10/2004 (6/26/2002)	MULTI-WAVELENGTH SEMICONDUCTOR LASER ARRAYS AND APPLICATIONS THEREOF Hamster, Harald; Trezza, John
6,633,421 (10/180,610)	US	10/14/2003 (6/26/2002)	INTEGRATED ARRAYS OF MODULATORS AND LASERS ON ELECTRONICS Trezza, John
6,613,597 (10/183,847)	US	9/2/2003 (6/27/2002)	OPTICAL CHIP PACKAGING VIA THROUGH HOLE Stack, Richard
CA2447345	CA	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Trezza, John; Dudoff, Greg
EP02749716.3	EP	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
KR10-2003-7016822	KR	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
SG101695 (SG20030757-1)	SG	(6/28/2002)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
DE60216119 (DE60216119)	DE	9/6/2007 (6/28/2002)	INTEGRATED ARRAYS OF MODULATORS AND LASERS ON ELECTRONICS Trezza, John
FR1417712 (FR02749717.1)	FR	11/15/2006 (6/28/2002)	INTEGRATED ARRAYS OF MODULATORS AND LASERS ON ELECTRONICS Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
GB1417712 (GB02749717.1)	GB	11/15/2006 (6/28/2002)	INTEGRATED ARRAYS OF MODULATORS AND LASERS ON ELECTRONICS Trezza, John
KR10-2003-7016824	KR	6/28/2002	OPTICAL CHIP PACKAGING VIA THROUGH HOLE Stack, Richard
CA2447364	CA	6/28/2002	TOPSIDE ACTIVE OPTICAL DEVICE APPARATUS AND METHOD Faska, Tom; Dudoff, Greg
CN02813185.1	CN	6/28/2002	Topside active optical device apparatus and method Faska, Tom; Dudoff, Greg
EP02749969.8	EP	6/28/2002	TOPSIDE ACTIVE OPTICAL DEVICE APPARATUS AND METHOD Faska, Tom; Dudoff, Greg
KR10-2003-7016816	KR	6/28/2002	TOPSIDE ACTIVE OPTICAL DEVICE APPARATUS AND METHOD Faska, Tom; Dudoff, Greg
SG101700 (SG200307584-3)	SG	(6/28/2002)	TOPSIDE ACTIVE OPTICAL DEVICE APPARATUS AND METHOD Faska, Tom; Dudoff, Greg
CA2447365	CA	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
ZL02813097.9 (CN02813097.9)	CN	9/6/2006 (6/28/2002)	Opto-electronic device integration Dudoff, Greg; Trezza, John
EP02753370.2	EP	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
KR10-2003-7016812	KR	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
SG200307578-5	SG	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
CA2447368	CA	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
CN02813089.8	CN	6/28/2002	Opto-electronic device integration Trezza, John; Hamster, Harald
KR10-2003-7016813	KR	6/28/2002	Opto-electronic device integration Trezza, John; Hamster, Harald
SG101307 (SG20030579-3)	SG	(6/28/2002)	Opto-electronic device integration Trezza, John; Hamster, Harald
DE60219161.0-08	DE	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
FR02756474.9	FR	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
GB1399953 (GB02756474.9)	GB	3/28/2007 (6/28/2002)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
CA2447369	CA	6/28/2002	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
ZL02813100.2 (CN02813100.2)	CN	11/15/2006 (6/28/2002)	Photoelectronic device integration Dudoff, Greg; Trezza, John
KR10-2003-701814	KR	6/28/2002	Photoelectronic device integration Dudoff, Greg; Trezza, John
SG101693 (SG200307573-6)	SG	11/15/2006 (6/28/2002)	Photoelectronic device integration Dudoff, Greg; Trezza, John
6,619,855 (10/098,255)	US	9/16/2003 (3/14/2002)	POST-FORMATION FEATURE OPTIMIZATION Dudoff, Greg; Kang, Keith;
6,609,835 (10/098,652)	US	8/26/2003 (3/14/2002)	Oxidized light guiding component and manufacturing technique Trezza, John; Kang, Keith; Dudoff, Greg

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
6,629,780 (10/098,990)	US	10/7/2003 (3/14/2002)	HIGH-PRECISION FEMALE FORMAT MULTIFIBER CONNECTOR Kang, Keith; Dudoff, Greg
6,722,788 (10/180,239)	US	4/20/2004 (6/26/2002)	INTEGRATION OF FUSED GLASS COLLIMATED COUPLER FOR USE IN OPTO-ELECTRONIC MODULES Kang, Keith; Trezza, John
CA2447370	CA	6/28/2002	HIGH-PRECISION FEMALE FORMAT MULTIFIBER CONNECTOR Dudoff, Greg; Kang, Keith
CN02813096.0	CN	6/28/2002	High-precision concave type multiple fiber optical connector Kang, Keith; Dudoff, Greg
KR10-2003-7016826	KR	6/28/2002	HIGH-PRECISION FEMALE FORMAT MULTIFIBER CONNECTOR Kang, Keith; Dudoff, Greg
SG101694 (SG200307574-4)	SG	(6/28/2002)	HIGH-PRECISION FEMALE FORMAT MULTIFIBER CONNECTOR Kang, Keith; Dudoff, Greg
CA2447341	CA	6/28/2002	POST-FORMATION FEATURE OPTIMIZATION Kang, Keith; Dudoff, Greg
ZL02813099.5 (CN02813099.5)	CN	6/28/2006 (6/28/2002)	Method of linker feature optimization Dudoff, Greg; Kang, Keith
KR10-2003-7016825	KR	6/28/2002	POST-FORMATION FEATURE OPTIMIZATION Dudoff, Greg; Kang, Keith
SG101699 (SG200307583-5)	SG	(6/28/2002)	POST-FORMATION FEATURE OPTIMIZATION Dudoff, Greg; Kang, Keith
6,899,465 (10/260,034)	US	5/31/2005 (6/26/2003)	MULTI-PIECE FIBER OPTIC COMPONENT AND MANUFACTURING TECHNIQUE Trezza, John; Kang, Keith; Dudoff, Greg; Olson, Ronald

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
7,077,577 (10/260,032)	US	7/18/2006 (6/27/2003)	MULTI-PIECE FIBER OPTIC COMPONENT AND MANUFACTURING TECHNIQUE Trezza, John; Kang, Keith; Dudoff, Greg; Olson, Ronald
6,945,701 (10/260,033)	US	9/20/2005 (6/27/2003)	MULTI-PIECE FIBER OPTIC COMPONENT AND MANUFACTURING TECHNIQUE Trezza, John; Kang, Keith; Dudoff, Greg; Olson, Ronald
6,817,778 (10/607,620)	US	11/16/2004 (6/27/2003)	HIGH-PRECISION FEMALE FORMAT MULTIFIBER CONNECTOR Kang, Keith; Dudoff, Greg
7,092,424 (10/676,281)	US	8/15/2006 (9/30/2003)	INTEGRATED ARRAYS OF MODULATORS AND LASERS ON ELECTRONICS Trezza, John
6,956,244 (10/793,509)	US	10/18/2005 (3/3/2004)	OPTO-ELECTRONIC DEVICE INTEGRATION Dudoff, Greg; Trezza, John
6,814,498 (10/817,190)	US	11/9/2004 (4/2/2004)	INTEGRATION OF FUSED GLASS COLLIMATED COUPLER FOR USE IN OPTO-ELECTRONIC MODULES Kang, Keith; Trezza, John
KR10-0709919 (KR10-2000-0046691)	KR	4/16/2007 (8/11/2000)	Apparatus for forming a TiN thin film and method of forming a MOCVD-TiN thin film using the same Kim, Byoung-Youp; Kim, Hyung-Seok
6,643,052 (09/788,714)	US	11/4/2003 (2/20/2001)	Apparatus comprising a micro-mechanical optical modulator Goossen, Keith W.
6,702,480 (09/872,903)	US	3/9/2004 (6/2/2001)	Opto-electronic chip package Sparacino, John
6,707,840 (09/873,640)	US	3/16/2004 (6/4/2001)	Vertical cavity surface emitting laser Goossen, Keith W.
6,771,860 (10/183,495)	US	8/3/2004 (6/27/2002)	Module mounted aligning optical connector Trezza, John; Kang, Keith
KR10-2003-7016823	KR	6/28/2002	Module mounted aligning optical connector Trezza, John; Kang, Keith

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
6,927,861 (10/183,766)	US	8/9/2005 (6/27/2002)	Simple deterministic method for array based optical component packaging Zhou, Chuang; Kang, Keith
6,804,438 (10/187,240)	US	10/12/2004 (6/28/2002)	Method for relaxing mechanical tolerance in an opto-electronic unit Stack, Richard; Dugas, Roger
6,857,788 (10/641,195)	US	2/22/2005 (8/13/2003)	Removable coupling of an opto-electronic module into a front access rack Dugas, Roger
CA2534536	CA	8/11/2004	REMOVABLE COUPLING OF AND OPTO-ELECTRONIC MODULE INTO A FRONT ACCESS RACK Dudoff, Greg
EP04780813.4	EP	8/11/2004	REMOVABLE COUPLING OF AND OPTO-ELECTRONIC MODULE INTO A FRONT ACCESS RACK Roger, Dugas
KR10-2006-7002837	KR	2/10/2006	REMOVABLE COUPLING OF AN OPTO-ELECTRONIC MODULE INTO A FRONT ACCESS RACK Dudoff, Greg
7,027,203 (10/391,431)	US	4/11/2006 (3/18/2003)	Combination micromachine and optical device array Trezza, John
CA2478238	CA	3/19/2003	COMBINATION MICROMACHINE AND OPTICAL DEVICE ARRAY Trezza, John
CN03806074.4	CN	3/19/2003	Combination micromachine and optical device array Trezza, John
KR10-2004-7014571	KR	3/19/2003	Combination micromachine and optical device array Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
EP03726079.1	EP	3/19/2003	COMBINATION MICROMACHINE AND OPTICAL DEVICE ARRAY Trezza, John
D466,865 (29/144,363)	US	12/10/2002 (6/29/2001)	COMMUNICATION MODULE Stack, Richard; Dugas, Roger
D466,866 (29/144,365)	US	(6/29/2001)	COMMUNICATION MODULE Stack, Richard; Dugas, Roger
D476,978 (29/157,414)	US	12/10/2002 (3/18/2002)	COMMUNICATION MODULE Dugas, Roger; Stack, Richard; Kang, Keith; Czoschke, Mark; Trezza, John
D476,979 (29/157,416)	US	7/8/2003 (3/18/2002)	COMMUNICATION MODULE Dugas, Roger; Stack, Richard; Kang, Keith; Czoschke, Mark; Trezza, John
D476,980 (29/157,420)	US	7/8/2003 (3/18/2002)	COMMUNICATION MODULE Dugas, Roger; Stack, Richard; Kang, Keith; Czoschke, Mark; Trezza, John
D477,312 (29/157,424)	US	7/15/2003 (3/18/2002)	COMMUNICATION MODULE Dugas, Roger; Stack, Richard; Kang, Keith; Czoschke, Mark; Trezza, John
D476,981 (29/157,454)	US	7/8/2003 (3/18/2002)	COMMUNICATION MODULE Dugas, Roger; Stack, Richard; Kang, Keith; Czoschke, Mark; Trezza, John
D476,982 (29/161,861)	US	7/8/2003 (6/4/2002)	COMMUNICATION INTERFACE Roger Dugas , Chester, NH (US)
D479,828 (29/172,257)	US	9/23/2003 (12/9/2002)	INSIDE-OUT HEAT SINK Dugas, Roger
D479,829 (29/172,258)	US	9/23/2003 (12/9/2002)	INSIDE-OUT HEAT SINK Dugas, Roger
D490,382 (29/172,246)	US	5/25/2004 (12/9/2002)	INSIDE-OUT HEAT SINK Dugas, Roger

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
D543,953 (29/189,322)	US	6/5/2007 (9/2/2003)	WING PORTION OF A BUTTERFLY-STYLE INSIDE-OUT HEAT SINK Dugas, Roger; Frushour, Ross L.
JP1240344 (JP2004-032771)	JP	4/1/2005 (10/28/2004)	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
EM000145354	EM	2/27/2004	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
EM000145354-0001	EM	6/1/2004 ()	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
(EM000145354-0002)	EM	6/1/2004 ()	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
(EM000145354-0003)	EM	6/1/2004 ()	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
(EM000145354-0004)	EM	6/1/2004 ()	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
(EM000145354-0005)	EM	6/1/2004 ()	BUTTERFLY-STYLE INSIDE-OUT HEAT SINK WING PORTION Dugas, Roger; Frushour, Ross L.
10/456,388	US	6/5/2003	Optical receiver device and method Faska, Tom; Martin, Robert

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
11/329,481	US	1/10/2006	Profiled contact Trezza, John; Callahan, John; Dudoff, Gregory
11/329,506	US	1/10/2006	Rigid-backed, membrane-based chip tooling Trezza, John; Frushour, Ross
11/329,539	US	1/10/2006	Membrane-based chip tooling Dugas, Roger; Trezza, John
11/329,540	US	1/10/2006	Routingless chip architecture Misra, Abhay; Trezza, John
11/329,556	US	1/10/2006	Post & penetration interconnection Trezza, John; Callahan, John; Dudoff, Gregory
11/329,557	US	1/10/2006	Remote chip attachment Trezza, John
11/329,558	US	1/10/2006	Chip-based thermo-stack Trezza, John
11/329,574	US	1/10/2006	Back-to-front via process Trezza, John
11/329,575	US	1/10/2006	Chip connector Trezza, John; Callahan, John; Dudoff, Gregory
11/329,576	US	1/10/2006	Patterned contact Trezza, John; Callahan, John; Dudoff, Gregory
11/329,852	US	1/10/2006	Through chip connection Trezza, John
11/329,873	US	1/10/2006	Post-attachment chip-to-chip connection Trezza, John
11/329,874	US	1/10/2006	Contact-based encapsulation Trezza, John; Callahan, John; Dudoff, Gregory
11/329,875	US	1/10/2006	Inverse chip connector Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
11/329,883	US	1/10/2006	Pin-type chip tooling Trezza, John; Frushour, Ross
11/329,885	US	1/10/2006	Electronic chip contact structure Trezza, John; Callahan, John; Dudoff, Gregory
11/329,886	US	1/10/2006	Chip spanning connection Trezza, John
7,215,032 (11/329,887)	US	5/8/2007 (1/10/2006)	TRIAXIAL THROUGH-CHIP CONNECTION Trezza, John
11/329,952	US	1/10/2006	Chip capacitive coupling Trezza, John
7,157,372 (11/329,953)	US	1/2/2007 (1/10/2006)	COAXIAL THROUGH CHIP CONNECTION Trezza, John
11/329,955	US	1/10/2006	Active packaging Trezza, John; Misra, Abhay
11/330,011	US	1/10/2006	Tack & fuse chip bonding Trezza, John; Callahan, John; Dudoff, Gregory
11/422,551	US	6/6/2006	ISOLATING CHIP-TO-CHIP CONTACT John Trezza , Nashua, NH (US)
PCT/US2006/023174	WO	6/14/2006	TACK & FUSE CHIP BONDING Trezza, John; Callahan, John; Dudoff, Gregory
PCT/US2006/023246	WO	6/14/2006	CHIP CONNECTOR Trezza, John; Callahan, John; Dudoff, Gregory
PCT/US2006/023248	WO	6/14/2006	THROUGH CHIP CONNECTION Trezza, John
PCT/US2006/023249	WO	6/14/2006	CHIP SPANNING CONNECTION Trezza, John
PCT/US2006/023250	WO	6/14/2006	ELECTRONIC CHIP CONTACT STRUCTURE Trezza, John; Callahan, John; Dudoff, Gregory

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
PCT/US2006/023297	WO	6/14/2006	ISOLATING CHIP-TO-CHIP CONTACT Trezza, John
PCT/US2006/023361	WO	6/14/2006	CHIP-BASED THERMO-STACK Trezza, John
PCT/US2006/023362	WO	6/14/2006	ROUTINGLESS CHIP ARCHITECTURE Trezza, John; Misra, Abhay
PCT/US2006/023363	WO	6/14/2006	BACK-TO-FRONT VIA PROCESS Trezza, John
PCT/US2006/023364	WO	6/14/2006	POST & PENETRATION INTERCONNECTION Trezza, John; Callahan, John; Dudoff, Gregory
PCT/US2006/023365	WO	6/14/2006	CHIP TOOLING Trezza, John; Frushour, Ross
PCT/US2006/023366	WO	6/14/2006	CHIP CAPACITIVE COUPLING Trezza, John
PCT/US2006/023367	WO	6/14/2006	ACTIVE PACKAGING Trezza, John; Misra, Abhay
PCT/US2006/023368	WO	6/14/2006	REMOTE CHIP ATTACHMENT Trezza, John
11/556,747	US	11/6/2006	Processed Wafer Via Trezza, John
11/556,826	US	11/6/2006	COAXIAL THROUGH CHIP CONNECTION Trezza, John
11/675,746	US	2/16/2007	THERMALLY BALANCED VIA Trezza, John
11/675,756	US	2/16/2007	STACKED CHIP-BASED SYSTEM AND METHOD Trezza, John

Patent or Application No.	Country	Filing Date	Title of Patent and Inventors
11/688,088	US	3/19/2007	Side Stacking Apparatus and Method Trezza, John
11/693,851	US	3/30/2007	TRIAXIAL THROUGH-CHIP CONNECTION Trezza, John
11/693,936	US	3/30/2007	CHIP CONNECTOR Trezza, John; Callahan, John; Dudoff, Gregory
11/693,984	US	3/30/2007	MEMBRANE-BASED CHIP TOOLING Dugas, Roger; Trezza, John
11/617,985	US	12/29/2006	FRONT-END PROCESSED WAFER HAVING THROUGH-CHIP CONNECTIONS Trezza, John
11/696,799	US	4/5/2007	FRONT-END PROCESSED WAFER HAVING THROUGH-CHIP CONNECTIONS Trezza, John
11/619,482	US	1/3/2007	IMPROVED SENSITIVITY CAPACITIVE No inventor(s) info available
11/675,268	US	2/15/2007	POST-SEET DEPOSITION PROCESS No inventor(s) info available
11/675,287	US	2/15/2007	VARIABLE OFF-CHIP DRIVE No inventor(s) info available
11/675,453	US	2/15/2007	BOWED WAFER HYBRIDIZATION COMPENSATION No inventor(s) info available
11/675,731	US	2/16/2007	PLATED PILAR PACKAGE FORMATION No inventor(s) info available
11/696,774	US	4/5/2007	HEAT CYCLE-ABLE CONNECTION No inventor(s) info available
11/696,796	US	4/5/2007	ANTI-PHASE SEGREGATION CONNECTION No inventor(s) info available

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11/738,817	US	4/23/2007	ULTRA-THIN CHIP PACKAGING No inventor(s) info available
11/778,461	US	7/16/2007	ELECTRICALLY CONDUCTIVE INTERCONNECT SYSTEM AND METHOD No inventor(s) info available
11/872,083	US	10/15/2007	WAFER VIA FORMATION No inventor(s) info available
PCT/US07/81380	WO	10/15/2007	WAFER VIA FORMATION No inventor(s) info available
7,289,547 (10/697,815)	US	10/30/2007 (10/29/2003)	LASER AND DETECTOR DEVICE Trezza, John; Diagne, Mohamed
EP04816927.0	EP	10/18/2004	LASER AND DETECTOR DEVICE TREZZA JOHN; DIAGNE MOHAMED
CN2004800321558	CN	10/18/2004	LASER AND DETECTOR DEVICE TREZZA JOHN; DIAGNE MOHAMED
KR10-2006-7008317	KR	10/18/2004	LASER AND DETECTOR DEVICE TREZZA JOHN; DIAGNE MOHAMED

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The terms and conditions of this Assignment of Patent Rights will inure to the benefit of Assignee, its successors, assigns, and other legal representatives and will be binding upon Assignor, its successors, assigns, and other legal representatives.

IN WITNESS WHEREOF this Assignment of Patent Rights is executed at AUSTIN, TX on 21 MARCH 2008.

ASSIGNOR:

Cubic Wafer, Inc.

By: Edmund G. Healy
Name: EDMUND G. HEALY
Title: CEO
(Signature MUST be notarized)

STATE OF Texas)
) ss.
COUNTY OF Travis)

On 3-21-08, before me, Margaret LaMore, Notary Public in and for said State, personally appeared Edmund G. Healy, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument and acknowledged to me that he/she executed the same in his/her authorized capacity, and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature Margaret LaMore (Seal)

MARGARET LAMORE
My Commission Expires
July 30, 2011